

L Number	Hits	Search Text	DB	Time stamp
1	152	257/778.ccls. and 257/784.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 16:21
2	70	(257/778.ccls. and 257/784.ccls.) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 17:40
3	4227	(flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 16:33
4	893	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 16:34
5	1065	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 16:35
6	194	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)) and (encapsulation or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/08/04 16:48
7	1	("6157080").PN.	USPAT	2004/08/04 16:48

L Number	Hits	Search Text	DB	Time stamp
1	2752	(chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:19
2	2064	((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:10
3	125	257/732.ccls. and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
4	111	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:27
5	108	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:22
6	0	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))) and lock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:23
7	16	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))) and lock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:23
8	26	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((depression or step) with ((cap or lid or encapsulant or encapsulate) and (lock or interlock or adhesive or adhesion)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:32
9	164	((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
10	164	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock))) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
11	153	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock))) and (@ad<20000317)) not (((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:34
-	1	("20040121515").PN.	USPAT; US-PGPUB	2004/08/04 16:19

-	152	257/778.ccls. and 257/784.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:21
-	70	(257/778.ccls. and 257/784.ccls.) and (@ad<20000317)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:40
-	4227	(flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:08
-	893	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:34
-	1065	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:35
-	194	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)) and (encapsulation or encapsulate)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:48
-	1	("6157080").PN.	USPAT	2004/08/04 16:48
-	2	"10335544"	JPO; DERWENT	2004/08/04 18:51
-	2	("6157080") or ("6071755").PN.	USPAT	2004/08/04 20:07

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1	2752	(chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:19
2	2064	((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:10
3	125	257/732.ccls. and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
4	111	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:27
5	108	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:22
6	0	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))) and lock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:23
7	16	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317))) and lock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:23
8	26	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((depression or step) with ((cap or lid or encapsulant or encapsulate) and (lock or interlock or adhesive or adhesion)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:32
9	164	((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
10	164	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock))) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:33
11	153	(((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((cap or lid or encapsulant or encapsulate) with (lock or interlock))) and (@ad<20000317)) not (((((chip or die) and ((cap or lid or encapsulant or encapsulate) with flange)) and (@ad<20000317)) and ((insulation or insulating or dielectric) with (cap or lid or encapsulant or encapsulate))) not (257/732.ccls. and (@ad<20000317)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:34
-	1	("20040121515").PN.	USPAT; US-PGPUB	2004/08/04 16:19

-	152	257/778.ccls. and 257/784.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:21
-	70	(257/778.ccls. and 257/784.ccls.) and (@ad<20000317)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 17:40
-	4227	(flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 20:08
-	893	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:34
-	1065	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:35
-	194	((flip adj chip) and wire and (@ad<20000317) and (chip or chips or die or dies)) and (passive or resistor or inductor or capacitor)) and (encapsulation or encapsulate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/04 16:48
-	1	("6157080").PN.	USPAT	2004/08/04 16:48
-	2	"10335544"	JPO; DERWENT	2004/08/04 18:51
-	2	("6157080") or ("6071755").PN.	USPAT	2004/08/04 20:07